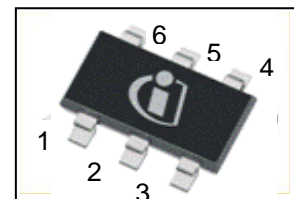
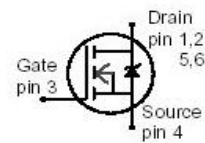


OptiMOS[®] 2 Small-Signal-Transistor
Features

- N-channel
- Enhancement mode
- Super Logic level (2.5V rated)
- Avalanche rated
- dv/dt rated
- Pb-free lead plating; RoHS compliant
- Qualified according to AEC Q101
- Halogen free according to IEC61249-2-21

Product Summary

| | | |
|------------------|-----------------------|----|
| V_{DS} | 20 | V |
| $R_{DS(on),max}$ | $V_{GS}=4.5\text{ V}$ | 22 |
| | $V_{GS}=2.5\text{ V}$ | 36 |
| I_D | 7.5 | A |

TSOP-6


| Type | Package | Tape and Reel Information | Marking | Lead Free | Packing |
|----------|---------|---------------------------|---------|-----------|---------|
| BSL202SN | TSOP-6 | H6327: 3000 pcs/ reel | sPD | Yes | Non dry |

Maximum ratings, at $T_j=25\text{ °C}$, unless otherwise specified

| Parameter | Symbol | Conditions | Value | Unit |
|-------------------------------------|-------------------|--|----------------|-------------------|
| Continuous drain current | I_D | $T_A=25\text{ °C}$ | 7.5 | A |
| | | $T_A=70\text{ °C}$ | 6.0 | |
| Pulsed drain current | $I_{D,pulse}$ | $T_A=25\text{ °C}$ | 30 | |
| Avalanche energy, single pulse | E_{AS} | $I_D=7.5\text{ A}$, $R_{GS}=25\ \Omega$ | 30 | mJ |
| Reverse diode dv/dt | dv/dt | $I_D=7.5\text{ A}$, $V_{DS}=16\text{ V}$, $di/dt=200\text{ A}/\mu\text{s}$, $T_{j,max}=150\text{ °C}$ | 6 | kV/ μs |
| Gate source voltage | V_{GS} | | ± 12 | V |
| Power dissipation ¹⁾ | P_{tot} | $T_A=25\text{ °C}$ | 2 | W |
| Operating and storage temperature | T_j , T_{stg} | | -55 ... 150 | °C |
| ESD Class | | JESD22-A114 -HBM | 0 (0V to 250V) | |
| Soldering Temperature | | | 260 °C | |
| IEC climatic category; DIN IEC 68-1 | | | 55/150/56 | |

| Parameter | Symbol | Conditions | Values | | | Unit |
|-----------|--------|------------|--------|------|------|------|
| | | | min. | typ. | max. | |

Thermal characteristics

| | | | | | | |
|--|------------|--|---|---|------|-----|
| Thermal resistance, junction - minimal footprint | R_{thJS} | | - | - | 50 | K/W |
| SMD version, device on PCB | R_{thJA} | minimal footprint | - | - | 230 | |
| | | 6 cm ² cooling area ¹⁾ | - | - | 62.5 | |

Electrical characteristics, at $T_j=25\text{ }^\circ\text{C}$, unless otherwise specified
Static characteristics

| | | | | | | |
|----------------------------------|---------------|--|-----|------|-----|---------------|
| Drain-source breakdown voltage | $V_{(BR)DSS}$ | $V_{GS}=0\text{ V}, I_D=250\text{ }\mu\text{A}$ | 20 | - | - | V |
| Gate threshold voltage | $V_{GS(th)}$ | $V_{DS}=V_{GS}, I_D=30\text{ }\mu\text{A}$ | 0.7 | 0.95 | 1.2 | |
| Drain-source leakage current | I_{DSS} | $V_{DS}=20\text{ V}, V_{GS}=0\text{ V}, T_j=25\text{ }^\circ\text{C}$ | - | - | 1 | μA |
| | | $V_{DS}=20\text{ V}, V_{GS}=0\text{ V}, T_j=150\text{ }^\circ\text{C}$ | - | - | 100 | |
| Gate-source leakage current | I_{GSS} | $V_{GS}=12\text{ V}, V_{DS}=0\text{ V}$ | - | - | 100 | nA |
| Drain-source on-state resistance | $R_{DS(on)}$ | $V_{GS}=2.5\text{ V}, I_D=5.9\text{ A}$ | - | 26 | 36 | m Ω |
| | | $V_{GS}=4.5\text{ V}, I_D=7.5\text{ A}$ | - | 17 | 22 | |
| Transconductance | g_{fs} | $ V_{DS} >2 I_D R_{DS(on)max}, I_D=7.5\text{ A}$ | | 25 | - | S |

¹⁾ Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm² (single layer, 70 μm thick) copper area for drain connection. PCB is vertical in still air. ($t < 5\text{ sec.}$)

| Parameter | Symbol | Conditions | Values | | | Unit |
|-----------|--------|------------|--------|------|------|------|
| | | | min. | typ. | max. | |

Dynamic characteristics

| | | | | | | |
|------------------------------|--------------|---|---|------|------|----|
| Input capacitance | C_{iss} | $V_{GS}=0\text{ V}, V_{DS}=10\text{ V},$ $f=1\text{ MHz}$ | - | 863 | 1147 | pF |
| Output capacitance | C_{oss} | | - | 278 | 370 | |
| Reverse transfer capacitance | C_{rss} | | - | 40 | 60 | |
| Turn-on delay time | $t_{d(on)}$ | $V_{DD}=10\text{ V}, V_{GS}=4.5\text{ V},$ $I_D=7.5\text{ A}, R_{G,ext}=6\ \Omega$ | - | 8.26 | - | ns |
| Rise time | t_r | | - | 27.5 | - | |
| Turn-off delay time | $t_{d(off)}$ | | - | 18.9 | - | |
| Fall time | t_f | | - | 4.06 | - | |

Gate Charge Characteristics

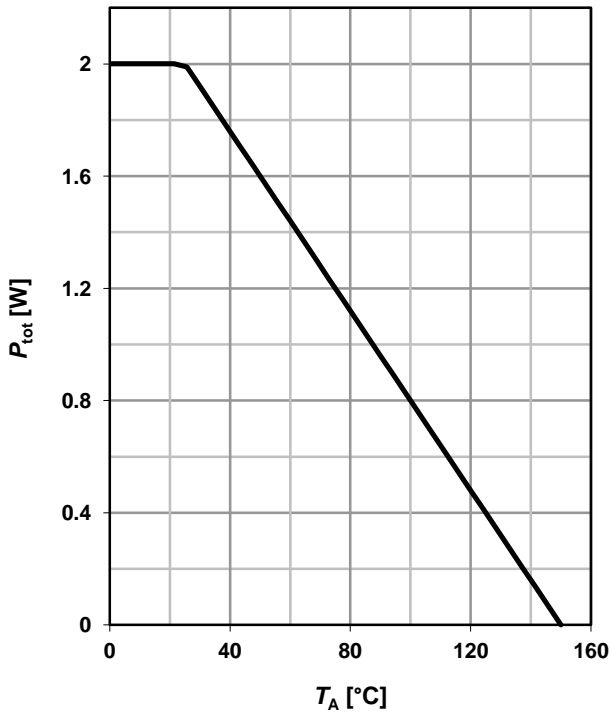
| | | | | | | |
|-----------------------|---------------|--|---|------|------|----|
| Gate to source charge | Q_{gs} | $V_{DD}=10\text{ V}, I_D=7.5\text{ A},$ $V_{GS}=0\text{ to }4.5\text{ V}$ | - | 1.82 | 2.42 | nC |
| Gate to drain charge | Q_{gd} | | - | 1.1 | 1.6 | |
| Gate charge total | Q_g | | - | 5.8 | 8.7 | |
| Gate plateau voltage | $V_{plateau}$ | | - | 2 | - | V |

Reverse Diode

| | | | | | | |
|----------------------------------|---------------|--|---|------|-----|----|
| Diode continuous forward current | I_S | $T_A=25\text{ }^\circ\text{C}$ | - | - | 2 | A |
| Diode pulse current | $I_{S,pulse}$ | | - | - | 30 | |
| Diode forward voltage | V_{SD} | $V_{GS}=0\text{ V}, I_F=7.5\text{ A},$ $T_j=25\text{ }^\circ\text{C}$ | - | 0.8 | 1.2 | V |
| Reverse recovery time | t_{rr} | $V_R=10\text{ V}, I_F=7.5\text{ A},$ $di_F/dt=100\text{ A}/\mu\text{s}$ | - | 14.7 | - | ns |
| Reverse recovery charge | Q_{rr} | | - | 4.62 | - | nC |

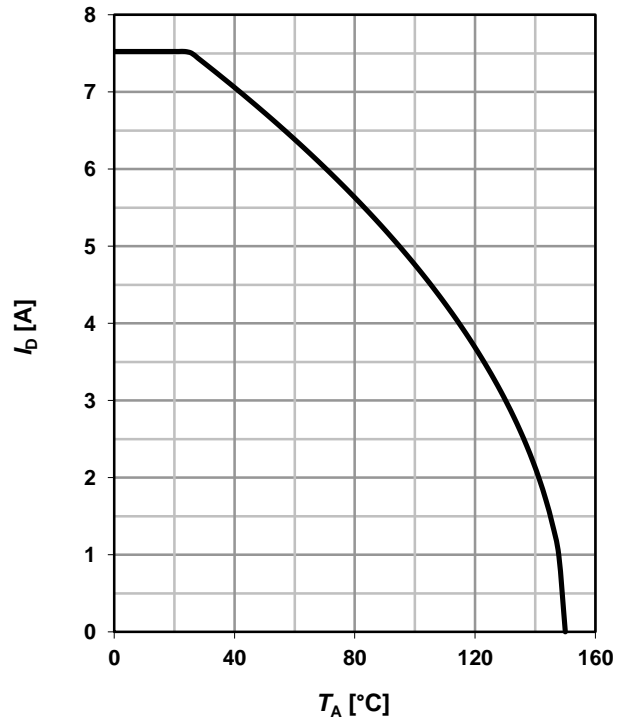
1 Power dissipation

$P_{tot}=f(T_A)$



2 Drain current

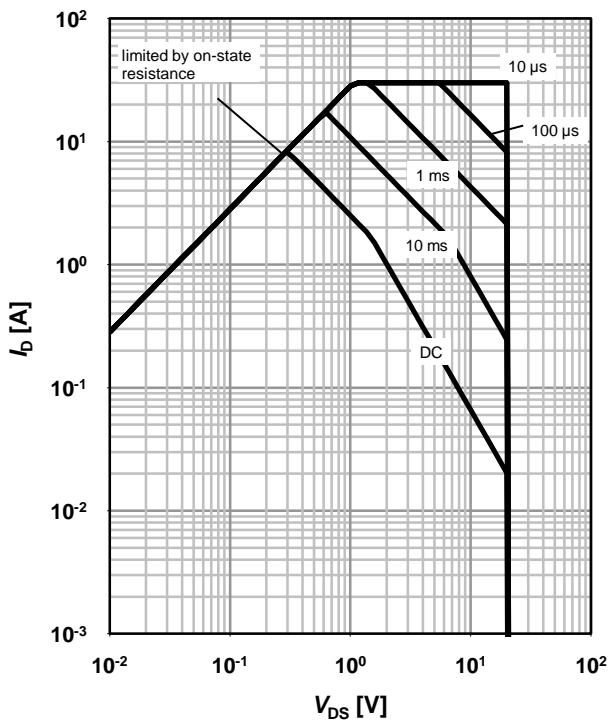
$I_D=f(T_A); V_{GS} \geq 4.5 V$



3 Safe operating area

$I_D=f(V_{DS}); T_A=25\text{ °C}; D=0$

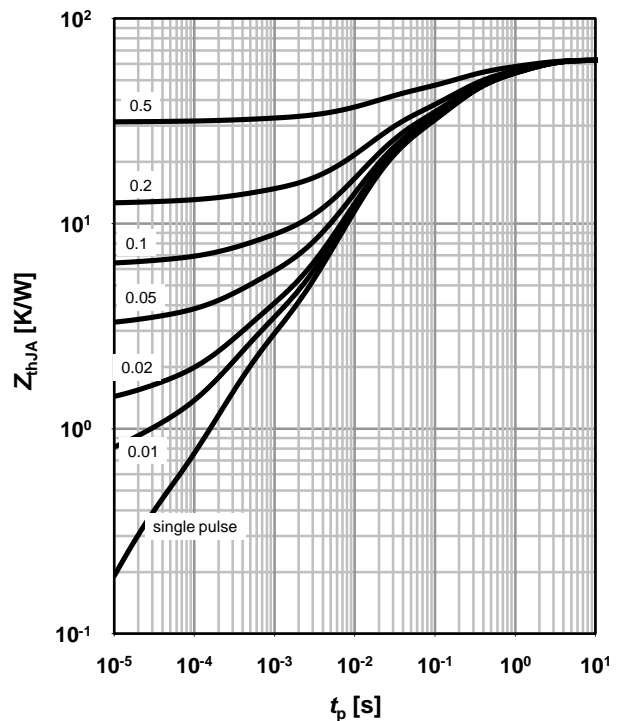
parameter: t_p



4 Max. transient thermal impedance

$Z_{thJA}=f(t_p)$

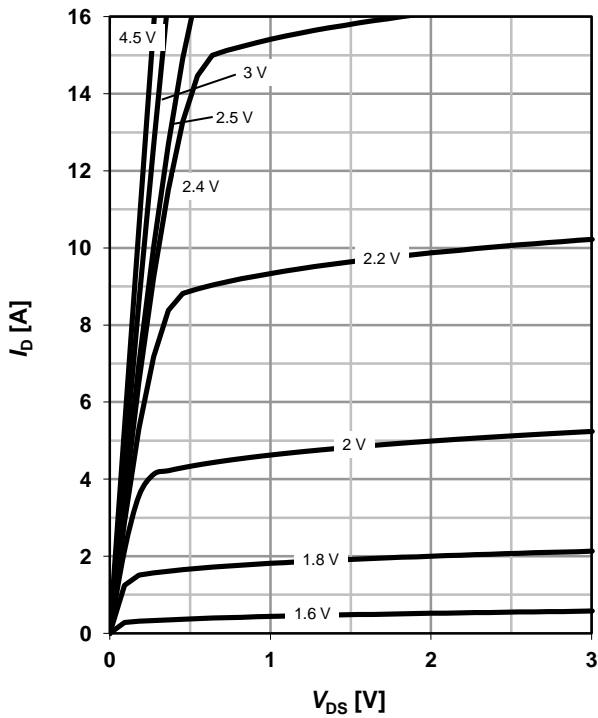
parameter: $D=t_p/T$



5 Typ. output characteristics

$I_D=f(V_{DS}); T_j=25\text{ }^\circ\text{C}$

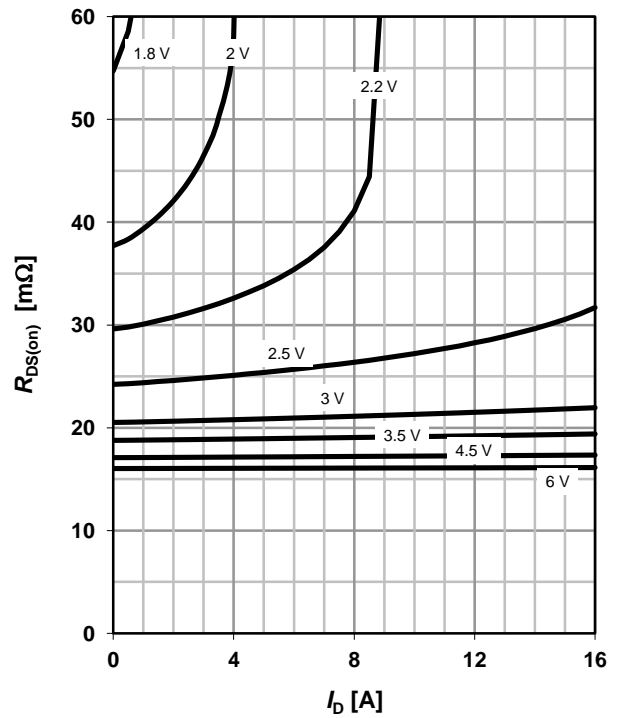
parameter: V_{GS}



6 Typ. drain-source on resistance

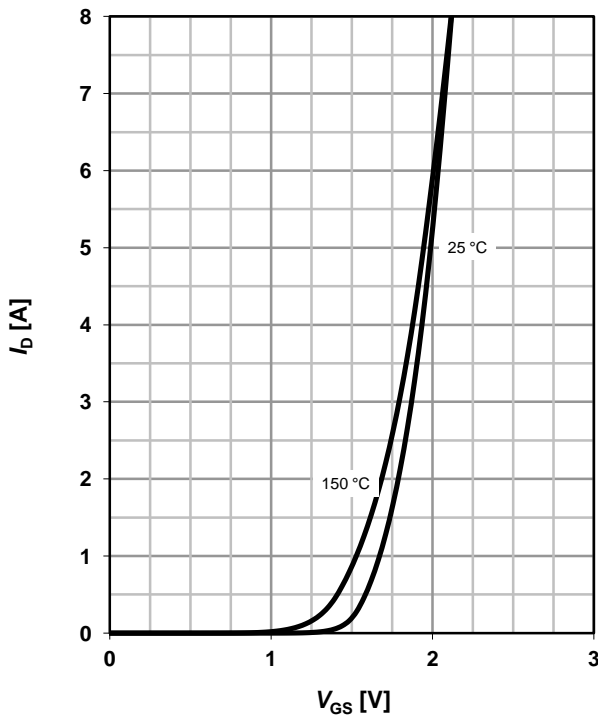
$R_{DS(on)}=f(I_D); T_j=25\text{ }^\circ\text{C}$

parameter: V_{GS}



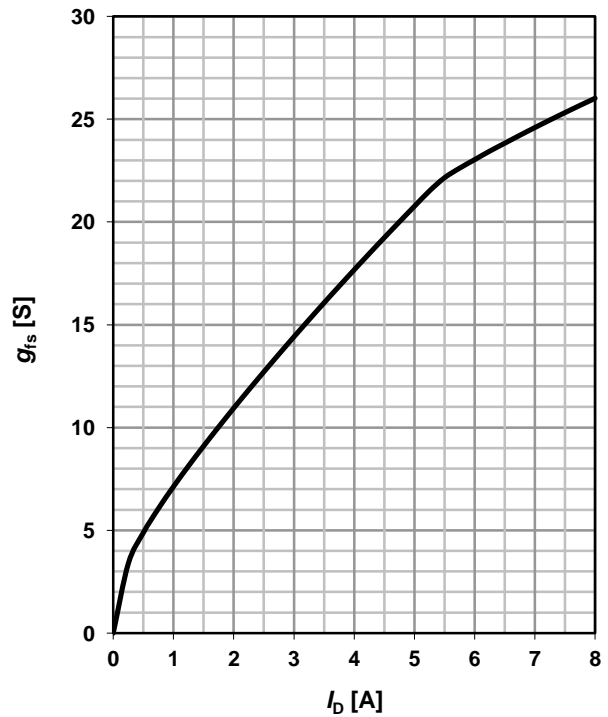
7 Typ. transfer characteristics

$I_D=f(V_{GS}); |V_{DS}|>2|I_D|R_{DS(on)max}$



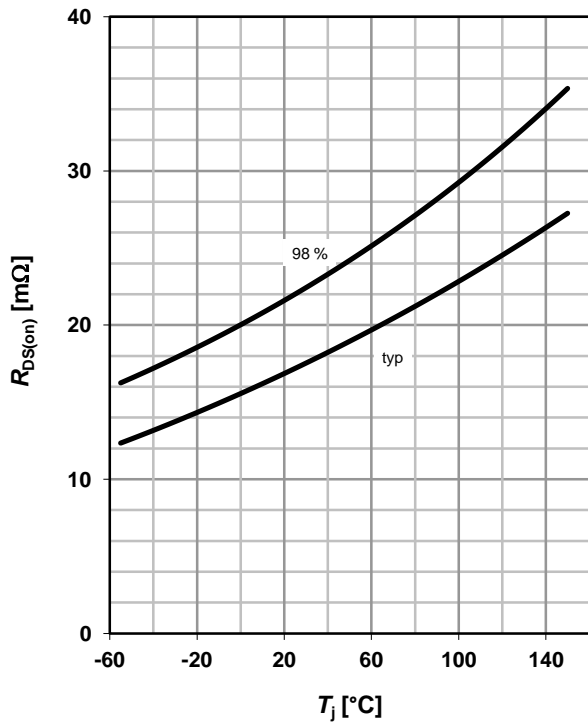
8 Typ. forward transconductance

$g_{fs}=f(I_D); T_j=25\text{ }^\circ\text{C}$



9 Drain-source on-state resistance

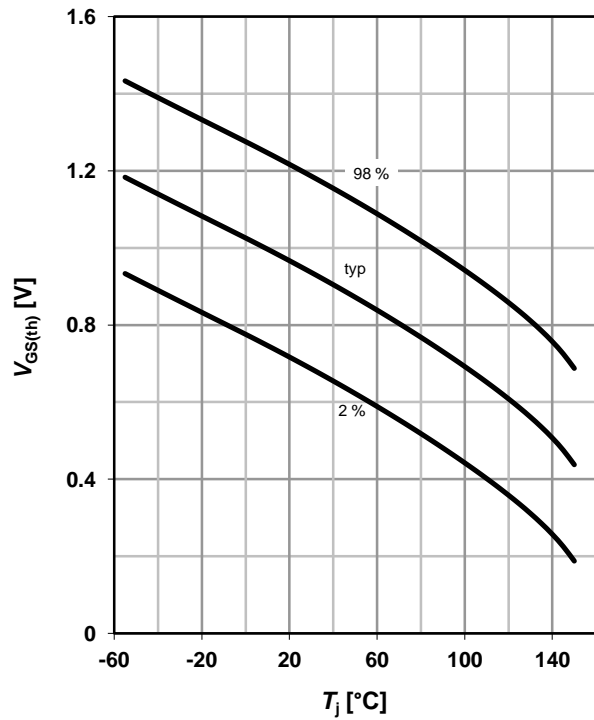
$R_{DS(on)}=f(T_j); I_D=7.5\text{ A}; V_{GS}=4.5\text{ V}$



10 Typ. gate threshold voltage

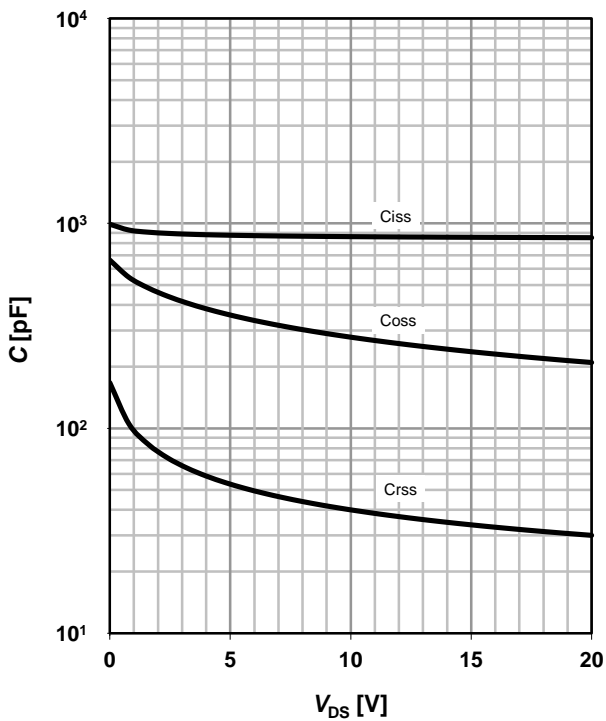
$V_{GS(th)}=f(T_j); V_{DS}=V_{GS}; I_D=30\ \mu\text{A}$

parameter: I_D



11 Typ. capacitances

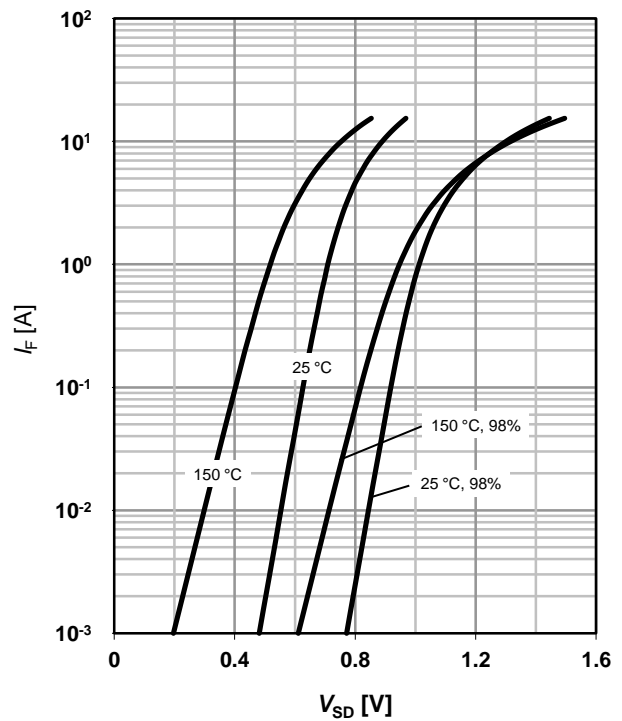
$C=f(V_{DS}); V_{GS}=0\text{ V}; f=1\text{ MHz}; T_j=25^\circ\text{C}$



12 Forward characteristics of reverse diode

$I_F=f(V_{SD})$

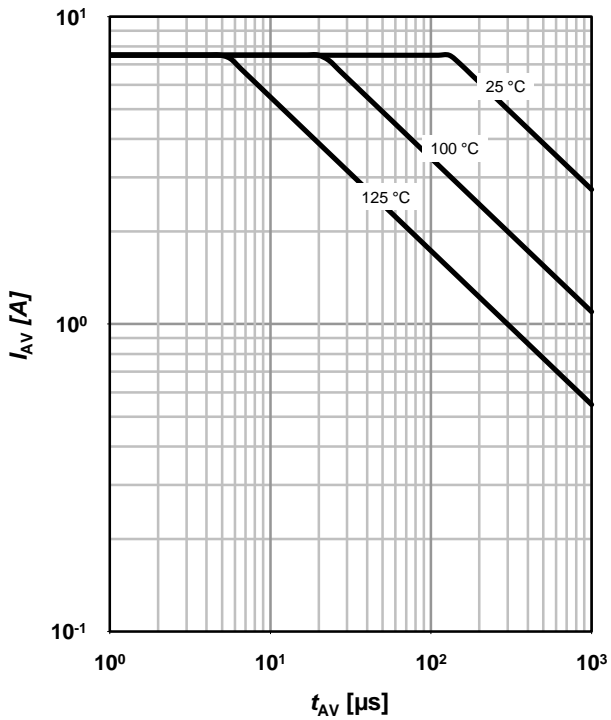
parameter: T_j



13 Avalanche characteristics

$I_{AS}=f(t_{AV}); R_{GS}=25 \Omega$

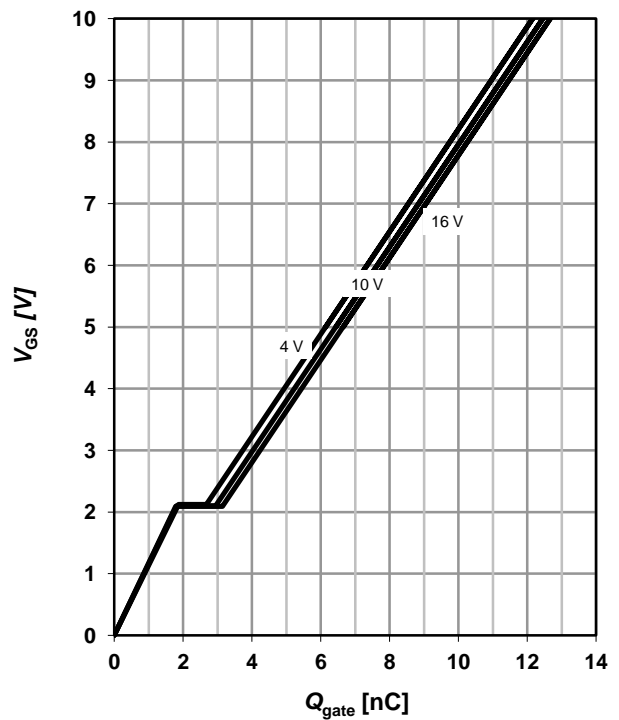
parameter: $T_{j(\text{start})}$



14 Typ. gate charge

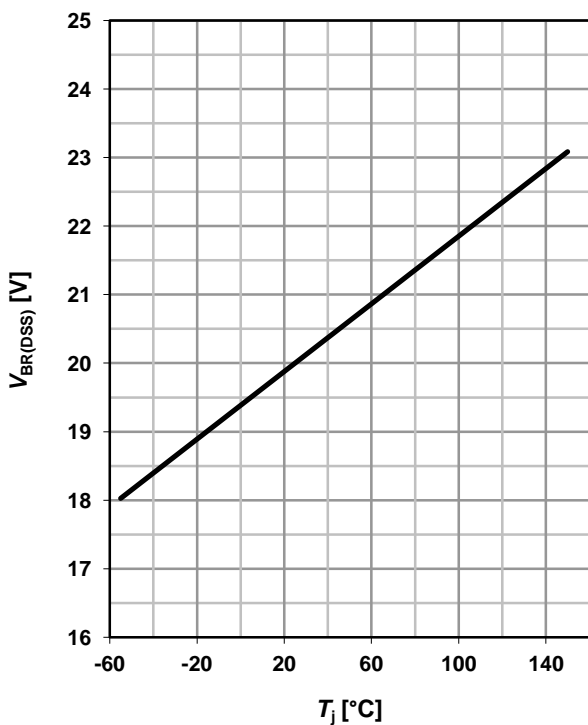
$V_{GS}=f(Q_{\text{gate}}); I_D=7.5 \text{ A pulsed}$

parameter: V_{DD}

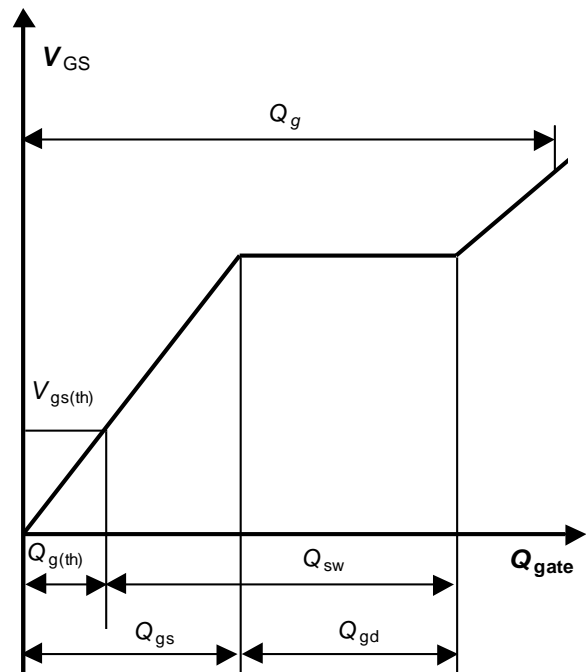


15 Drain-source breakdown voltage

$V_{BR(DSS)}=f(T_j); I_D=250 \mu\text{A}$



16 Gate charge waveforms



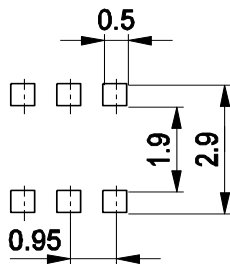
Package Outline:

TSOP6



GPX09300

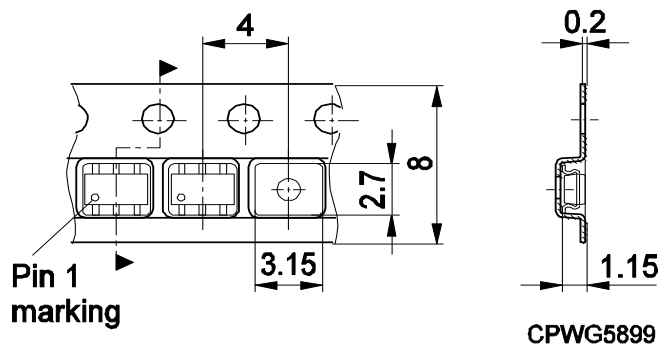
Footprint:



Remark: Wave soldering possible dep. on customers process conditions

HLG09283

Packaging:



CPWG5899

Dimensions in mm

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